SECOµSBC-i.MX6

Micro Single Board Computer with Freescale™ i.MX6 Processor

CPU
Single-, Dual- and Quad- Core (ARM Cortex™A9 Cores)

Memory
Up to 2GB DDR3L onboard

Graphics
2D/3D dedicated graphics processors

Temperature
Also available in Industrial temperature range, -40°C ÷ +85°C

ARM

FEATURES

	Processor	Freescale™ i.MX6 Family, based on ARM Cortex-A9 processors: Single core i.MX6S up to 1GHz Dual Core (i.MX6D), Dual Core Lite (i.MX6DL) up to 1.2GHz Quad Core (i.MX6Q) up to 1GHz clock
	Max Cores	4
	Memory	Up to 2GB DDR3L onboard (up to 1GB with i.MX6S)
	Graphics	integrated graphics, each processor provides up to 3 separated accelerators for 2D, OpenGL® ES2.0 3D and OpenVG™ (OpenVG™ accelerator only available with i.MX6D and with i.MX6Q) Supports up to 3 independent displays (up to 2 displays with i.MX6DL and i.MX6S)
	Video Interfaces	HDMI Connector 1 x Dual Channel or 2 x Single Channel 18/24 bit LVDS interface
	Video Resolution	LVDS, up to 1920x1200 HDMI, up to 1080p
	Mass Storage	eMMC soldered onboard mSATA slot for 30mm modules (only i.MX6Q and i.MX6D, shared with miniPCI-Express)
	Networking	Gigabit Ethernet connector
	USB	Up to 3 x standard USB 2.0 ports 1 x USB OTG Internal USB for optional WiFi module
	PCI-e	Half-mini PCI-e slot (shared with mSATA)
	Audio	AC'97 Audio Codec LineOut, Mic In internal connector
	Serial Ports	1 x RS-232 serial port CAN interface internal connector
	Power Supply	+12V$_{DC}$ Power Jack Optional cabled RTC battery
	Power Consumption	Embedded additional RTC circuitry for lowest power consumption
	Operating System	Linux
	Operating Temperature*	0°C ÷ +70 °C (commercial version) -40°C ÷ +85°C (industrial version)
	Dimensions	80 x 67 mm (3,15" x 2,64")

*Measured at any point of the heatspreader/heatsink during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider specific cooling solutions for the final system.

HIGHLIGHTS

- The power of the Freescale™ i.MX6 SoC in a credit card sized SBC

- Scalable multi-core ARM® Cortex™-A9 architecture

- It combines and emphasizes high-graphics performance with power-efficient processing capabilities

- Flexible solution suitable for digital signage applications. A multi-display platform for mobile fanless applications

- Best cost-benefit ratio

freescale™

MAIN FIELDS OF APPLICATION

Point of Sales

Digital Signage - Infotainment

Please visit **www.seco.com** for thermal dissipation information

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